Power line chokes

Current-compensated ring core double chokes
250 V AC, 0.5 … 6.8 mH, 4.3 … 10 A, +70 °C / +80 °C

Series/Type: B82724J2*U
Date: July 2015
Power line chokes

**Current-compensated ring core double chokes**

- Rated voltage 250 V AC
- Rated inductance 0.5 ... 6.8 mH
- Rated current 4.3 ... 10 A / +70 °C / +80 °C

**Construction**
- Current-compensated ring core double chokes
- Ferrite core with epoxy coating (UL 94 V-0)
- Plastic case (UL 94 V-0, CTI600)
- Full potting (UL 94 V-0, CTI600)
- Sector winding

**Features**
- High resonance frequency due to special winding technique
- Approx. 0.1 ... 1.0% stray inductance for symmetrical interference suppression
- High rated currents and rated temperatures
- Suitable for wave soldering
- Design complies with EN 60938-2 (VDE 0565-2) and UL 1283
- UL1) and VDE/ ENEC (VDE) approvals
- Construction approved to EN 60335-1 (VDE 0700-1)2)
- RoHS-compatible

**Applications**
- Suppression of common-mode interferences
- Switch-mode power applications
- Household appliances (white goods)
- Frequency converters for motor control and drives

** Terminals**
- Base material CuNi18Zn290
- Layer composition Ni, Sn
- Pins 0.7 mm x 0.7 mm
- Lead spacing 15 mm x 12.5 mm

** Marking**
Product brand, electrical insulation system designation, ordering code, rated voltages, rated inductance, rated current, date of manufacture (YYWWD.internal ID code), production place identification code

**Delivery mode**
- Blister tray in cardboard box

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1) UL approval with 300 V AC
2) Certified values:
   - Glow wire test (GWT to IEC 60695-2-11): +750 °C, 2 s / +850 °C, 30 s
   - Tracking index (PTI[A] to IEC 60112): ≥ 250 V
   - Ball pressure test (BP to IEC 60695-10-2): +125 °C

Please read **Cautions and warnings** and **Important notes** at the end of this document.
Dimensional drawings and pin configurations

Part tolerances to ISO 2768-cL / ISO 8015.
Size ISO 14405
All dimensions in mm

Please read Cautions and warnings and Important notes at the end of this document.
Technical data and measuring conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Rated voltage $V_R$</td>
<td>250 V AC (50 / 60 Hz)</td>
</tr>
<tr>
<td>Test voltage $V_{test}$</td>
<td>1500 V AC, 2 s (line/line)</td>
</tr>
<tr>
<td>Rated temperature $T_R$</td>
<td>$+70^\circ C$ / $+80^\circ C$</td>
</tr>
<tr>
<td>Rated current $I_R$</td>
<td>Referred to 50 Hz and rated temperature</td>
</tr>
<tr>
<td>Rated inductance $L_R$</td>
<td>Measured with Agilent 4284A at 0.1 mA, $+20^\circ C$</td>
</tr>
<tr>
<td></td>
<td>Measuring frequency: $L_R \leq 1 \text{ mH}: f = 100 \text{ kHz}$</td>
</tr>
<tr>
<td></td>
<td>$L_R &gt; 1 \text{ mH}: f = 10 \text{ kHz}$</td>
</tr>
<tr>
<td>Inductance tolerance</td>
<td>$\pm 30%$ at $+20^\circ C$</td>
</tr>
<tr>
<td>Inductance decrease $\Delta L/L_0$</td>
<td>$&lt; 10%$ at DC magnetic bias with $I_R$, $+20^\circ C$</td>
</tr>
<tr>
<td>Stray inductance $L_{\text{stray,typ}}$</td>
<td>Measured with Agilent 4284A at 5 mA, $+20^\circ C$, typical values</td>
</tr>
<tr>
<td></td>
<td>Measuring frequency: $L_R \leq 1 \text{ mH}: f = 100 \text{ kHz}$</td>
</tr>
<tr>
<td></td>
<td>$L_R &gt; 1 \text{ mH}: f = 10 \text{ kHz}$</td>
</tr>
<tr>
<td>DC resistance $R_{\text{typ}}$</td>
<td>Measured at $+20^\circ C$, typical values, specified per winding</td>
</tr>
<tr>
<td>Solderability (lead-free)</td>
<td>Sn96.5Ag3.0Cu0.5: $+(245 \pm 5)^\circ C$, $(3 \pm 0.3)$ s</td>
</tr>
<tr>
<td></td>
<td>Wetting of soldering area $\geq 95%$ (to IEC 60068-2-20, test Ta)</td>
</tr>
<tr>
<td>Resistance to soldering heat</td>
<td>$+(260 \pm 5)^\circ C$, $(10 \pm 1)$ s</td>
</tr>
<tr>
<td>(wave soldering)</td>
<td>(to IEC 60068-2-20, test Tb)</td>
</tr>
<tr>
<td>Climatic category$^1$</td>
<td>40/125/56 (to IEC 60068-1)</td>
</tr>
<tr>
<td>Pollution degree</td>
<td>P3 (to IEC 61558-1)</td>
</tr>
<tr>
<td>Storage conditions (packaged)</td>
<td>$-25^\circ C$ ... $+40^\circ C$, $\leq 75%$ RH</td>
</tr>
<tr>
<td>Approvals</td>
<td>EN 60938-2, UL 1283</td>
</tr>
</tbody>
</table>

$^1$ Operating temperature: $-40^\circ C$ ... $+125^\circ C$, UL approval only with max. $+115^\circ C$
(see also the curve "Current derating vs. temperature" in this data sheet)

Characteristics and ordering codes

<table>
<thead>
<tr>
<th>$I_R$ A</th>
<th>$L_R$ mH</th>
<th>$L_{\text{stray,typ}}$ μH</th>
<th>$R_{\text{typ}}$ mΩ</th>
<th>$T_R$ °C</th>
<th>Ordering code</th>
<th>Approvals</th>
</tr>
</thead>
<tbody>
<tr>
<td>4.3</td>
<td>6.8</td>
<td>31</td>
<td>50</td>
<td>+70</td>
<td>B82724J2432U040</td>
<td>x</td>
</tr>
<tr>
<td>4.5</td>
<td>2.7</td>
<td>25</td>
<td>36</td>
<td>+80</td>
<td>B82724J2452U020</td>
<td>x</td>
</tr>
<tr>
<td>5.0</td>
<td>5.3</td>
<td>25</td>
<td>36</td>
<td>+70</td>
<td>B82724J2502U040</td>
<td>x</td>
</tr>
<tr>
<td>6.0</td>
<td>4.0</td>
<td>20</td>
<td>25</td>
<td>+70</td>
<td>B82724J2602U040</td>
<td>x</td>
</tr>
<tr>
<td>10.0</td>
<td>0.5</td>
<td>3.5</td>
<td>9</td>
<td>+70</td>
<td>B82724J2103U040</td>
<td>x</td>
</tr>
</tbody>
</table>

Please read **Cautions and warnings** and **Important notes** at the end of this document.
Impedance $|Z|$ versus frequency $f$
measured with windings in parallel at $+20\,^\circ\mathrm{C}$,
typical values

![Impedance graph]

Current derating $I_{\text{op}}/I_R$ versus ambient temperature $T_A$
rated temperature $T_R=+70\,^\circ\mathrm{C}/+80\,^\circ\mathrm{C}$
standard:

![Current derating graph]

Current derating $I_{\text{op}}/I_R$ versus ambient temperature $T_A$
rated temperature $T_R=+70\,^\circ\mathrm{C}/+80\,^\circ\mathrm{C}$
UL approval:

![Current derating UL approval graph]
Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.

- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation. Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.

- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.

- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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Please read Cautions and warnings and Important notes at the end of this document.
Important notes

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